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Kikuchi et al.

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[54] APPARATUS FOR SPIN COATING, A METHOD FOR SPIN COATING AND A METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

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[*] Notice: This patent issued on a continued pros-

ecution application filed under 37 CFR 1.53(d), and is subject to the twenty year patent term provisions of 35 U.S.C.

154(a)(2).

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[30] Foreign Application Priority Data

	Int. Cl. ⁷	3/782;
[58]	43 Field of Search	
	437/228, 231; 134/1.3, 34, 36; 438 778, 780	3/763,

[56] References Cited

U.S. PATENT DOCUMENTS

4,393,807	7/1983	Fujimura 118/52
4,510,176	4/1985	Cuthbert et al 118/52
4,564,280	1/1986	Fukuda 118/52
4,668,334	5/1987	Doornveld 118/52
4,685,975	8/1987	Kottman et al 427/273

(List continued on next page.)

FOREIGN PATENT DOCUMENTS

0 183 297	6/1986	European Pat. Off
0 403 086	12/1990	European Pat. Off
58-97835	7/1983	Japan .
60-138925	7/1985	Japan .
61-15773	1/1986	Japan .
61-150332	7/1986	Japan .
61-238050	10/1986	Japan .
62-117321	5/1987	Japan .
63-148633	6/1988	Japan .
1-58375	3/1989	Japan .
2-133916	5/1990	Japan .
2-73727	6/1990	Japan .
3-252124	11/1991	Japan .
4-98823	3/1992	Japan .
4-300674	10/1992	Japan .
4-305270	10/1992	Japan .

OTHER PUBLICATIONS

Search Report for G.B application 9,409,655.9.

Japanese Abstract of patent No. 3-76109 of Apr. 1991 by Toshiro Tsumori vol. 52 E 1080.

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[57] ABSTRACT

The invention relates to an apparatus for spin coating for forming a resist film, an SOG film, a polyimide film, and the like in manufacturing semiconductor devices and has the object of forming a coated film with a specified and uniform thickness even in case that an amount of discharged coating solution is a little. An apparatus for spin coating of the invention comprises a rotatable table for placing a wafer, a coating solution discharging means which is set above the rotatable table and discharges a coating solution on the surface of the wafer, and a solvent discharging means which is above the rotatable table and discharges a solvent capable of dissolving the coating solution.

5 Claims, 10 Drawing Sheets

